

描述 / Descriptions

表面贴装肖特基整流二极管，反向电压：20V~200V，正向电流：1.0A，SMA封装。
Surface Mount Schottky Barrier Rectifiers, Reverse Voltage：20 to 200V, Forward Current: 1.0A, SMA package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

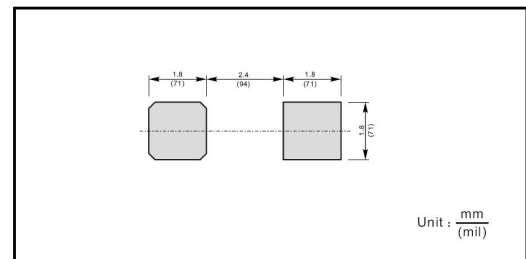


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating								单位 Unit
		SS12	SS14	SS16	SS18	SS110	SS112	SS115	SS120	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current Tc=100°C	$I_{F(AV)}$	1.0								A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25								A
Typical Junction Capacitance at $V_R=4V$ $f=1MHz$	C_j	110		80						pF
Typical Thermal Resistance ¹⁾	$R_{\theta JA}$ $R_{\theta JC}$	90 15								°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150								°C

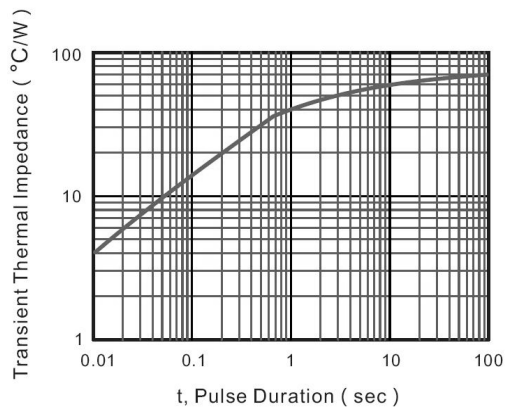
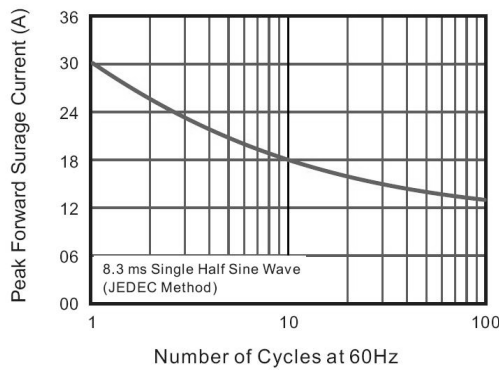
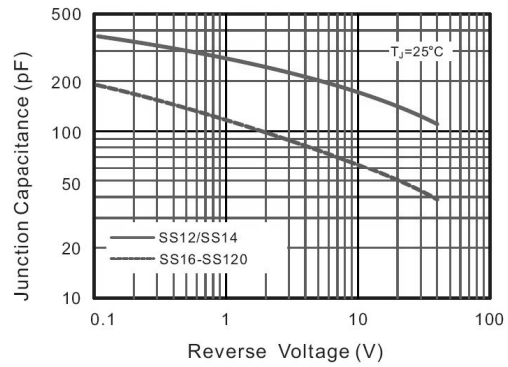
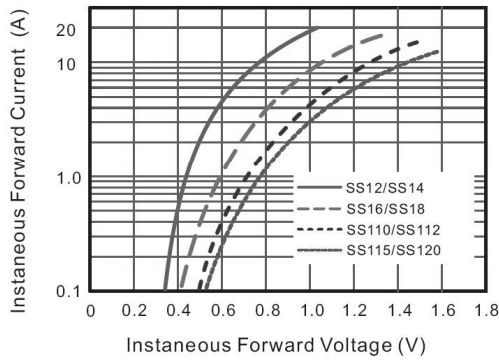
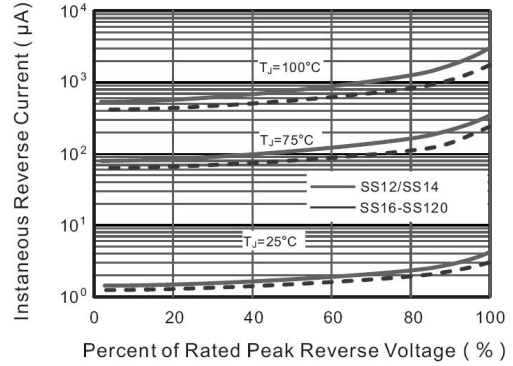
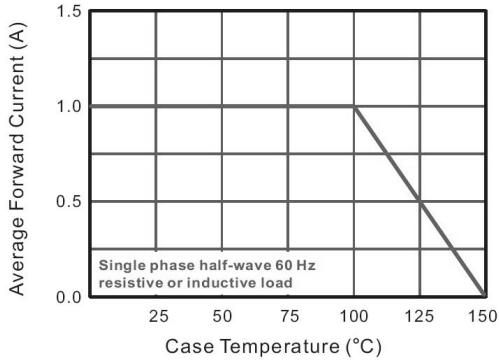
Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

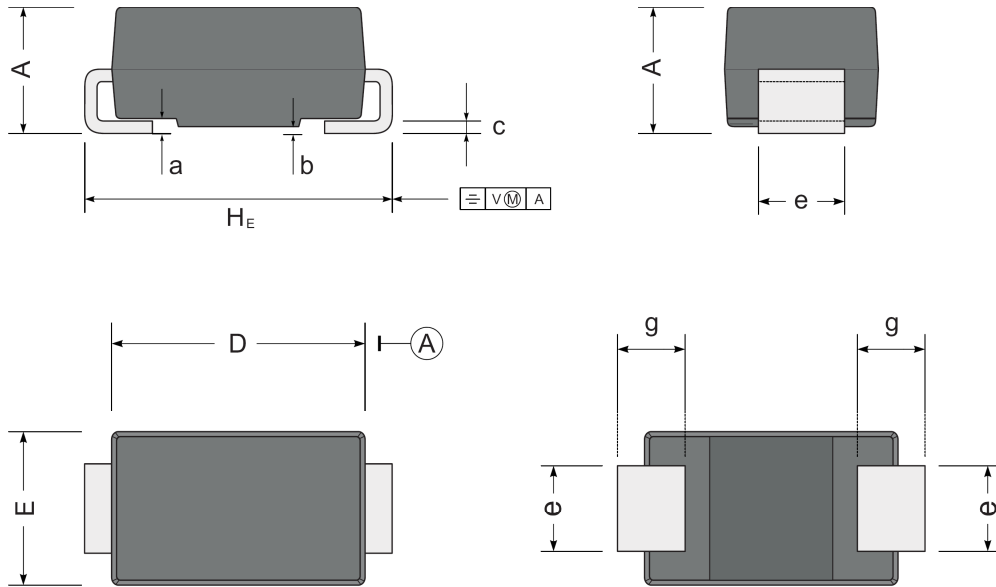
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating								单位 Unit
			SS12	SS14	SS16	SS18	SS110	SS112	SS115	SS120	
Maximum Instantaneous Forward Voltage	V_F	$I_F=1.0A$	0.55		0.70	0.85			0.90	V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ C$	0.3			0.2			0.1	mA	
		$T_a=100^\circ C$	10			5.0			2.0	mA	

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SMA



UNIT		A	D	E	H _E	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

印章说明 / Marking Instructions

Type number	Marking code
SS12	SS12
SS14	SS14
SS16	SS16
SS18	SS18
SS110	SS110
SS112	SS112
SS115	SS115
SS120	SS120



说明：

SS12： 为型号代码

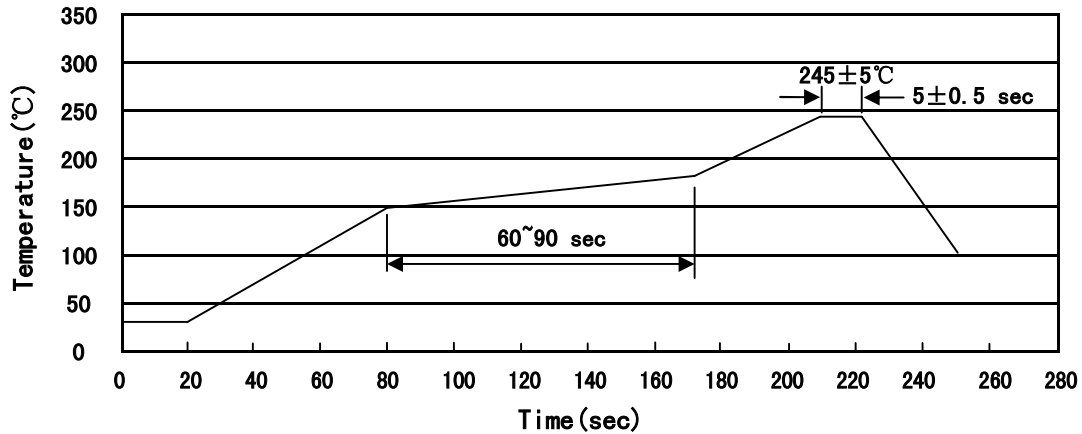
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

SS12： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No
Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMA	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

使用说明 / Notices